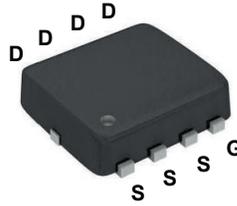
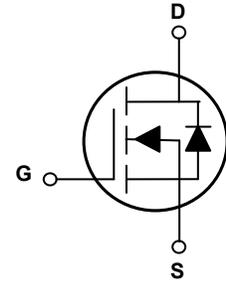


### Main Product Characteristics

$BV_{DSS}$	80V
$R_{DS(ON)}$	6.3m $\Omega$ (Typ.)
$I_D$	77A



PPAK3x3



Schematic Diagram

### Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



### Description

The GSGN8R77 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supplies and a wide variety of other applications.

### Absolute Maximum Ratings (T<sub>C</sub>=25°C unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V <sub>DS</sub>	80	V
Gate-Source Voltage	V <sub>GS</sub>	±20	V
Drain Current-Continuous	I <sub>D</sub>	77	A
Drain Current-Continuous (T <sub>C</sub> =100°C)		48	A
Pulsed Drain Current	I <sub>DM</sub>	308	A
Maximum Power Dissipation	P <sub>D</sub>	75	W
Derating Factor		0.6	W/°C
Single Pulse Avalanche Energy <sup>1</sup>	E <sub>AS</sub>	231	mJ
Thermal Resistance, Junction-to-Case	R <sub>θJC</sub>	1.66	°C/W
Operating Junction and Storage Temperature Range	T <sub>J</sub> /T <sub>STG</sub>	-55 To +150	°C

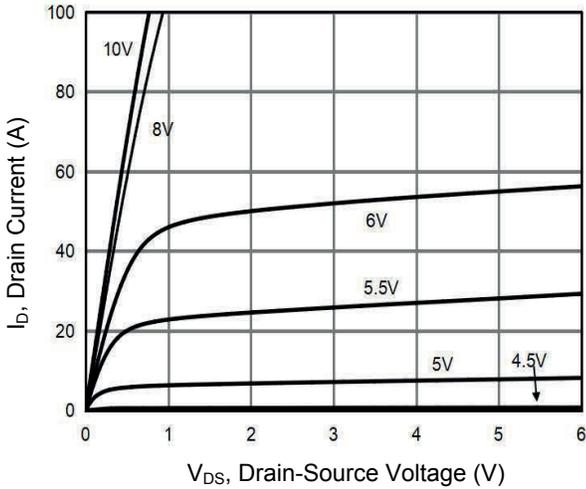
**Electrical Characteristics** ( $T_C=25^\circ\text{C}$  unless otherwise specified)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>On / Off Characteristics</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	80	-	-	V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=80V, V_{GS}=0V$	-	-	1	$\mu A$
Gate-Body Leakage Current	$I_{GSS}$	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	$\pm 100$	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	2	3.3	4	V
Drain-Source On-State Resistance	$R_{DS(on)}$	$V_{GS}=10V, I_D=20A$	-	6.3	7.5	m $\Omega$
Forward Transconductance	gfs	$V_{DS}=10V, I_D=20A$	-	45	-	S
<b>Dynamic and Switching Characteristics</b>						
Input Capacitance	$C_{iss}$	$V_{DS}=40V, V_{GS}=0V,$ $F=1.0MHz$	-	1420	-	pF
Output Capacitance	$C_{oss}$		-	775.8	-	
Reverse Transfer Capacitance	$C_{rss}$		-	26.9	-	
Turn-on Delay Time <sup>2</sup>	$t_{d(on)}$	$V_{DD}=40V, I_D=20A,$ $V_{GS}=10V, R_G=3\Omega$	-	9.1	-	nS
Turn-on Rise Time <sup>2</sup>	$t_r$		-	4.7	-	
Turn-Off Delay Time <sup>2</sup>	$t_{d(off)}$		-	20	-	
Turn-Off Fall Time <sup>2</sup>	$t_f$		-	5	-	
Total Gate Charge <sup>2</sup>	$Q_g$	$V_{DS}=40V, I_D=20A,$ $V_{GS}=10V$	-	23.9	-	nC
Gate-Source Charge <sup>2</sup>	$Q_{gs}$		-	9.1	-	
Gate-Drain Charge <sup>2</sup>	$Q_{gd}$		-	5.2	-	
<b>Source-Drain Ratings and Characteristics</b>						
Diode Forward Voltage	$V_{SD}$	$V_{GS}=0V, I_S=20A$	-	-	1.2	V
Diode Forward Current	$I_S$	-	-	-	77	A
Reverse Recovery Time	$T_{rr}$	$T_J=25^\circ\text{C}, I_F=20A,$ $di/dt=100A/\mu s$	-	50	-	nS
Reverse Recovery Charge	$Q_{rr}$		-	74	-	nC

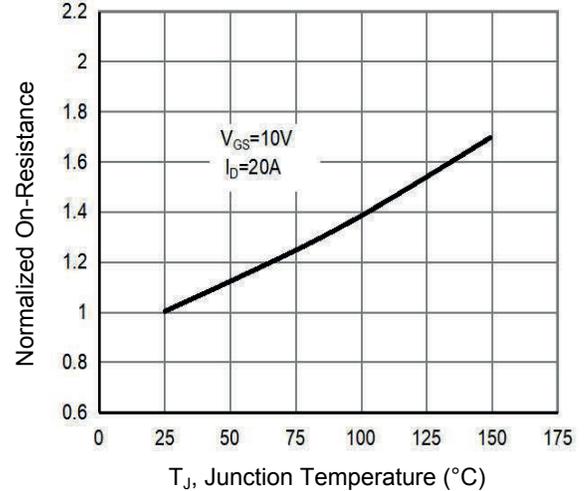
Notes:

1. Eas condition:  $T_J=25^\circ\text{C}, V_{DD}=40V, V_G=10V, L=0.5mH, R_g=25\Omega$ .
2. Guaranteed by design, not subject to production.
3. These curves are based on the junction-to-case thermal impedance which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of  $T_{J(MAX)}=150^\circ\text{C}$ . The SOA curve provides a single pulse rating.

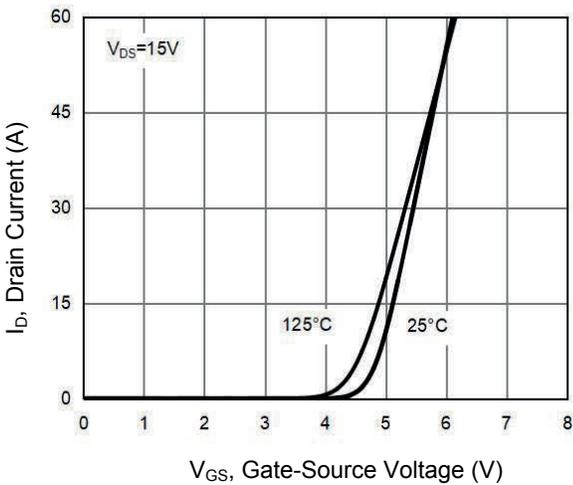
**Typical Electrical and Thermal Characteristic Curves**



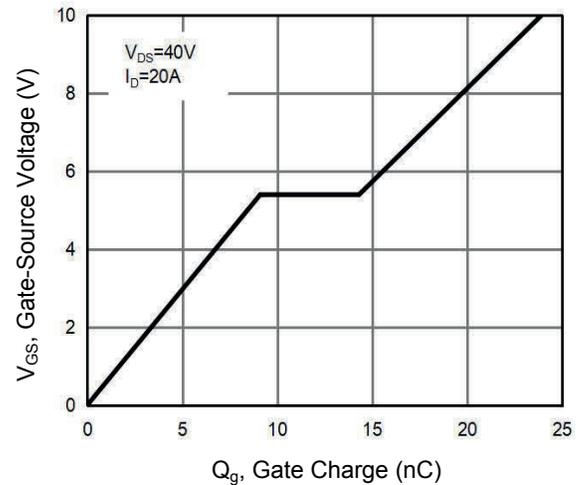
**Figure 1. Output Characteristics**



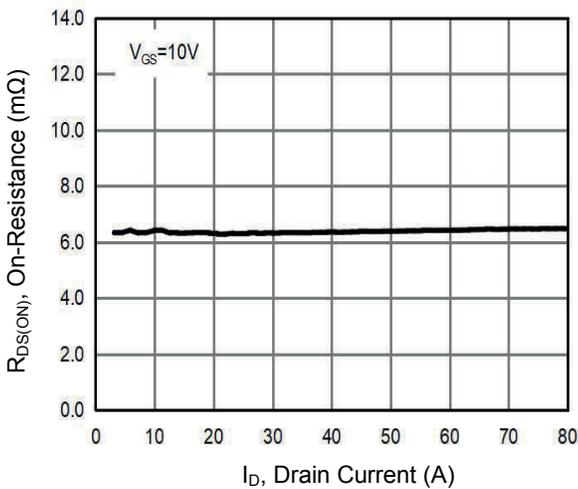
**Figure 2.  $R_{DS(ON)}$  vs. Junction Temperature**



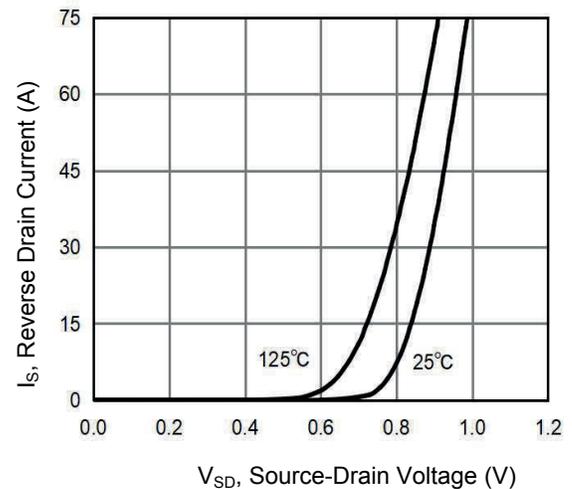
**Figure 3. Transfer Characteristics**



**Figure 4. Gate Charge**

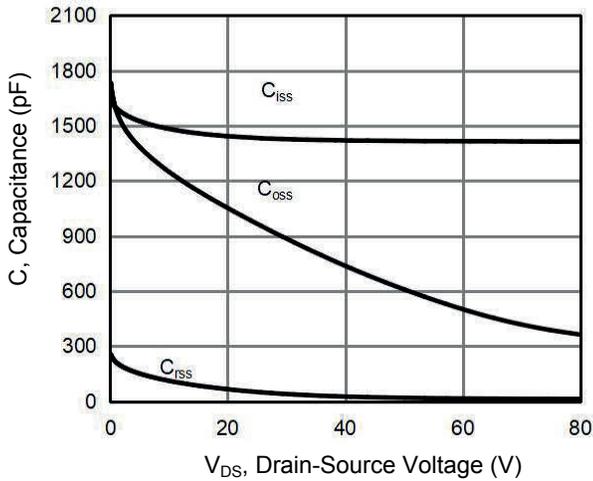


**Figure 5.  $R_{DS(ON)}$  vs. Drain Current**

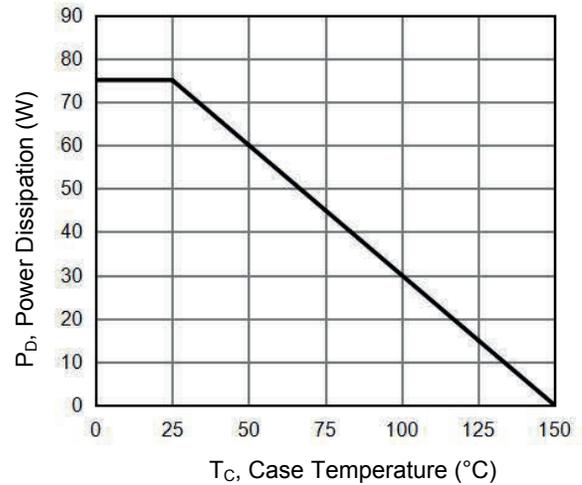


**Figure 6. Source-Drain Diode Forward Voltage**

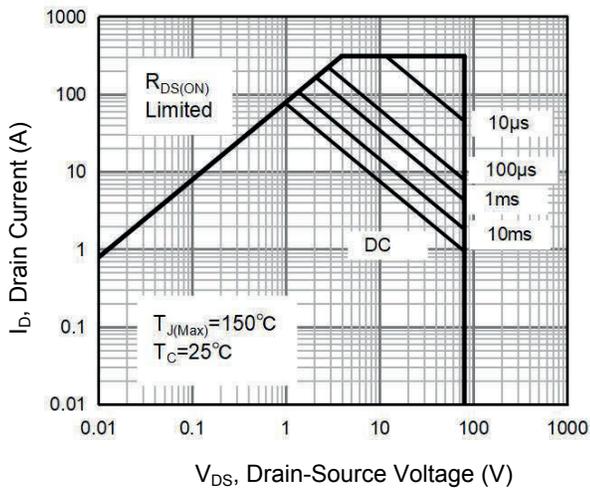
**Typical Electrical and Thermal Characteristic Curves**



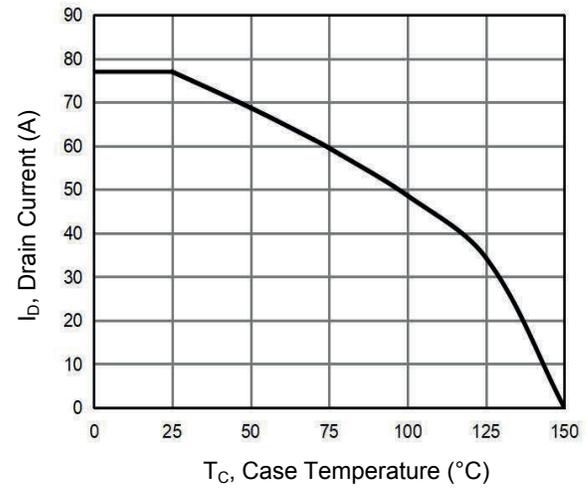
**Figure 7. Capacitance vs.  $V_{DS}$**



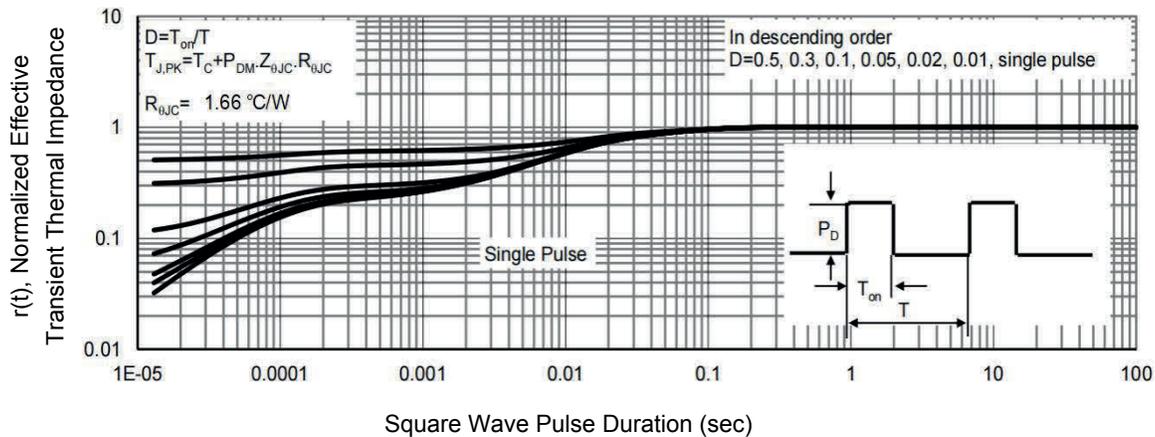
**Figure 8. Power De-rating**



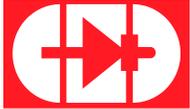
**Figure 9. Safe Operation Area<sup>3</sup>**



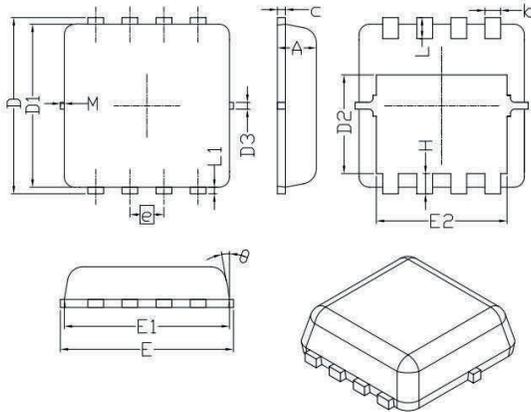
**Figure 10. Current De-rating**



**Figure 11. Normalized Maximum Transient Thermal Impedance**

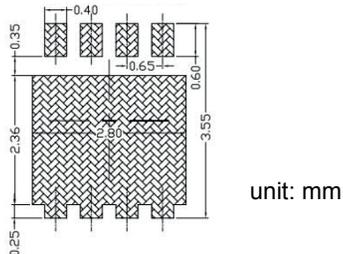


## Package Outline Dimensions (PPAK3x3)



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.70	0.80	0.028	0.031
b	0.25	0.35	0.010	0.014
c	0.10	0.25	0.004	0.010
D	3.25	3.45	0.128	0.136
D1	3.00	3.20	0.118	0.126
D2	1.78	1.98	0.070	0.078
D3	0.13 NOM		0.005 NOM	
E	3.10	3.30	0.122	0.130
E1	3.00	3.20	0.118	0.126
E2	2.39	2.59	0.094	0.102
e	0.65 BSC		0.026 BSC	
H	0.30	0.50	0.012	0.020
L	0.30	0.50	0.012	0.020
L1	0.13 NOM		0.005 NOM	
θ	-	12°	-	12°
M	-	0.15	-	0.006

## Recommended Pad Layout



## Order Information

Device	Package	Marking	Packaging	SPQ
GSGN8R77	PPAK3x3	N8R77	Tape & Reel	5,000 pcs / Reel

For more information, please contact us at: [inquiry@goodarksemi.com](mailto:inquiry@goodarksemi.com)